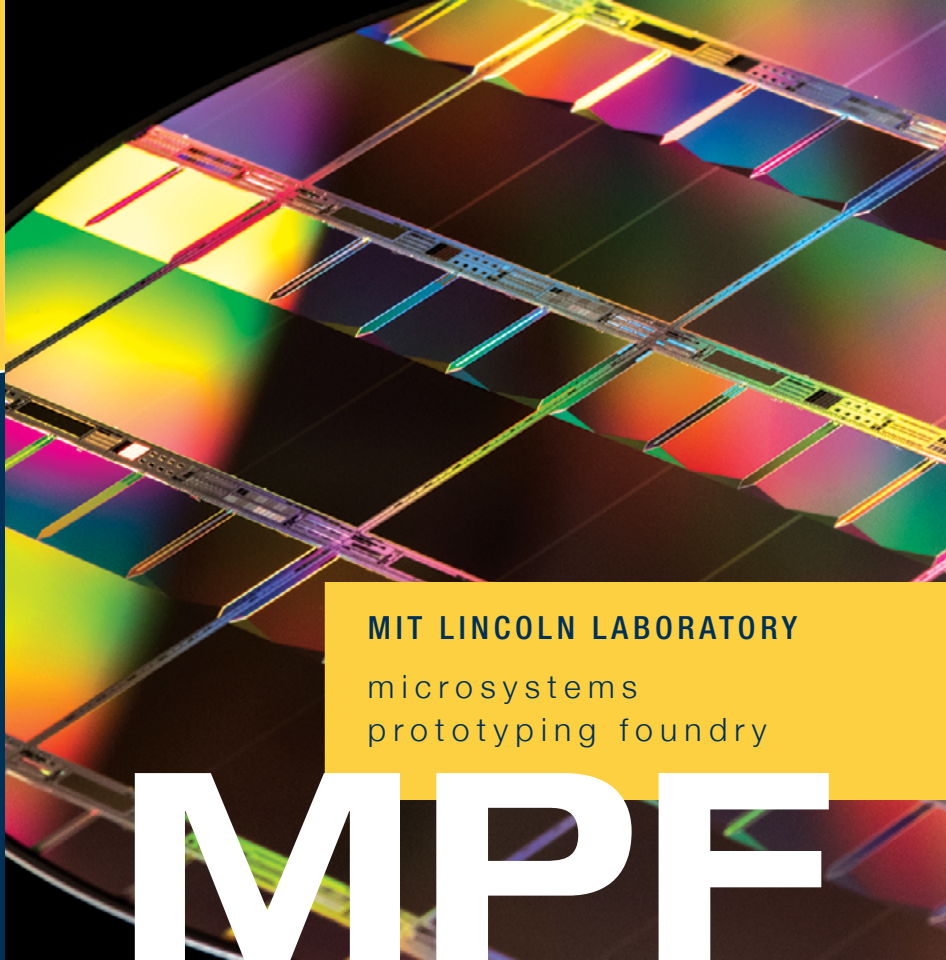

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prototyping foundry

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MPF specs

- 18,000-square-foot ISO 4 (Class 10) cleanroom
- 5 projection lithography platforms, including 193 nanometer
- More than 100 process tools
- 24-hour operation 5 days a week
- Custom circuits in multiple technologies

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inside the MPF PROCESS EQUIPMENT LAYOUT

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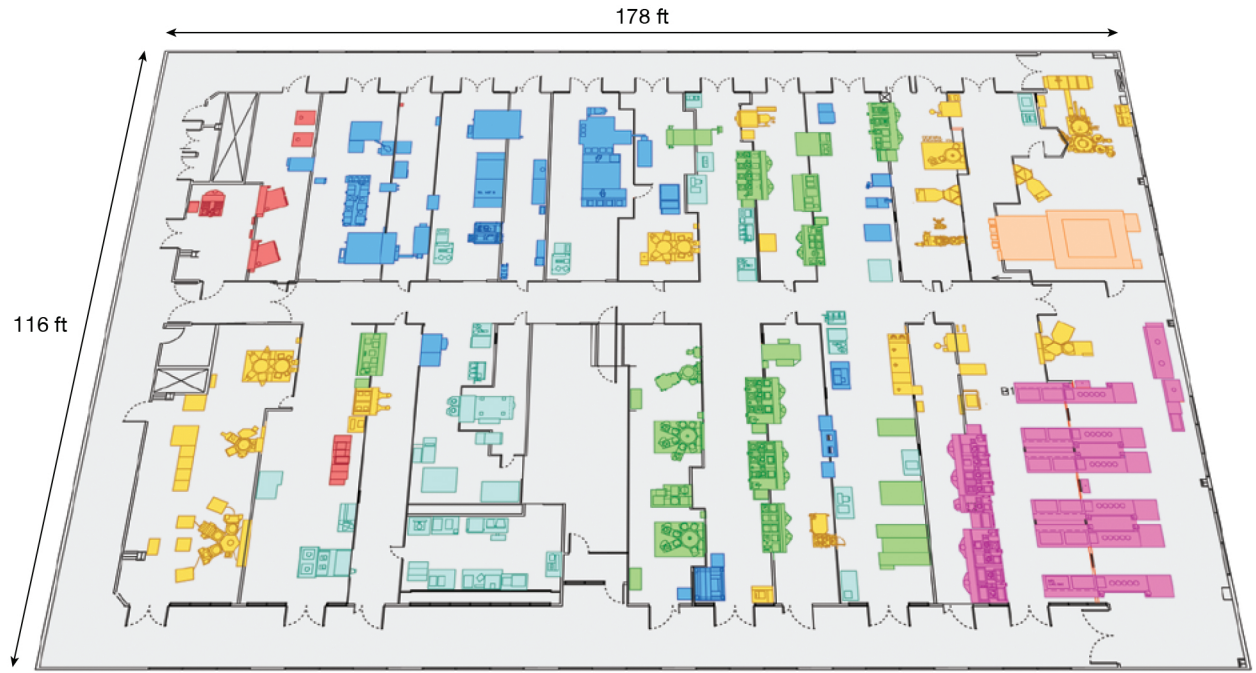

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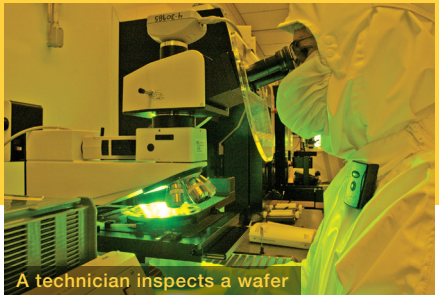
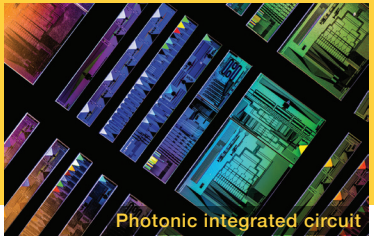
- 4-nanometer electron beam writing
- Molecular-beam epitaxy
- DMEA Category 1A Trusted Design, Aggregation, Foundry Services, Post Processing, and Packaging/Assembly accreditation and ISO 9001:2015 certification



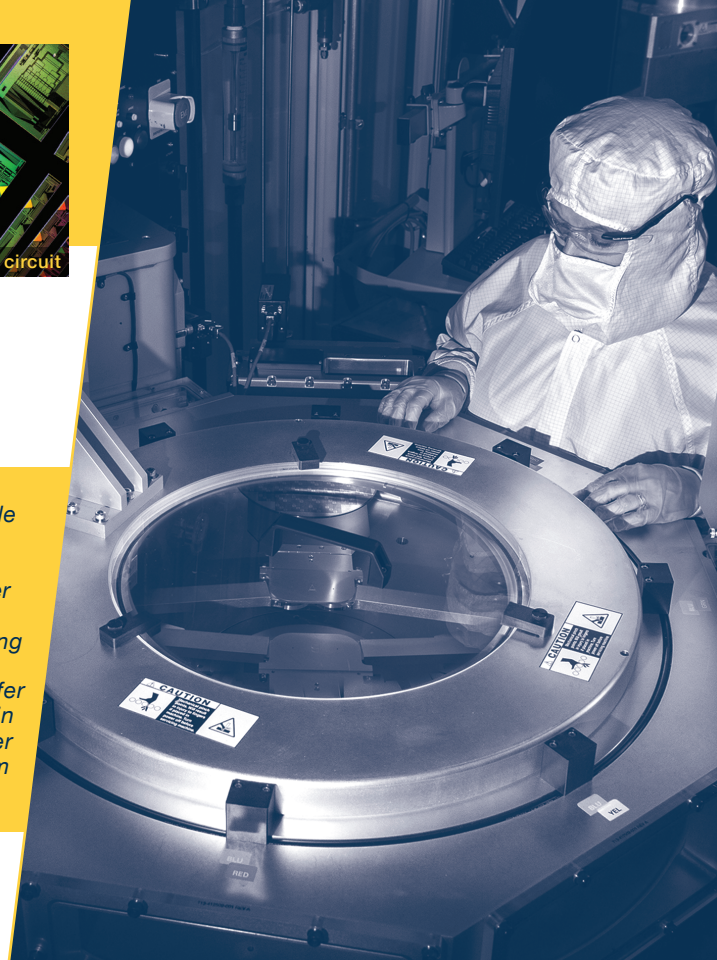
A technician inspects a wafer



Photonic integrated circuit

At left: *A reticle is loaded into a pod for 193-nanometer lithography wafer patterning*

At right: *A wafer is transferred in a multichamber cluster vacuum system*



interested?

Contact us at **MEL.Director@ll.mit.edu**

Information on how to engage in a test agreement is at **www.ll.mit.edu/testagreements**

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